

PCG3N60C3W

PRELIMINARY

January 2002

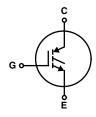
6A, 600V, UFS Series N-Channel IGBTs

Features

- 6A, 600V at T_C = 25°C
- 600V Switching SOA Capability

Formerly developmental type TA49113.

Symbol



Electrical Specifications $T_C = 25^{\circ}C$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CON	IDITIONS	MIN	TYP	MAX	UNITS
Collector to Emitter Breakdown Voltage	BV _{CES}	$I_C = 250 \mu A, V_{GE} =$	0V	600	-	-	V
Collector to Emitter Leakage Current	I _{CES}	V _{CE} = BV _{CES}	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	-	250	μΑ
Collector to Emitter Saturation Voltage	V _{CE(SAT)}	I _C = I _{C110} , V _{GE} = 15V	$T_C = 25^{\circ}C$	-	1.65	2.0	V
Gate to Emitter Threshold Voltage	V _{GE(TH)}	I _C = 250μA, V _{CE} = V _{GE}	$T_C = 25^{\circ}C$	3.0	5.5	6.0	V
Gate to Emitter Leakage Current	I _{GES}	V _{GE} = ±25V		-	-	±250	nA

Die Characteristics

DIE DIMENSIONS:

74 mils x 98 mils x 14 mils

WAFER DIAMETER:

5in with Standard Flat

PASSIVATION:

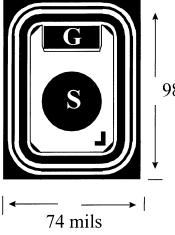
Nitride Thickness: 17kÅ ±1.5kÅ

FRONTSIDE METALLIZATION:

Type: Al

Metallization Mask Layout

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S = SOURCE = 32mils ROUND G = GATE = 32 X 16mils

98 mils

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